

6/8inch General PVD System

Model: SA-eVictor AX20P

SA-eVictor AX20P is a cluster-type 6/8-inch front-side PVD system dedicated to Si/SiC power devices and advanced logic chips. It realizes sputtering deposition of Ti, TiN, AlCu, NiV and Ag for ohmic contact, barrier layer and pad metallization. With strict film uniformity below 3% and particle count under 30ea@0.3μm, the equipment has been fully validated for mass production with stable film performance and outstanding cost efficiency.



Feature

- Cluster multi-chamber architecture
- Low particle contamination
- Mass production
- Compatible with sputtering

Application

- Si/SiC Power
- Ohmic Contact
- Barrier Layer
- Planarization

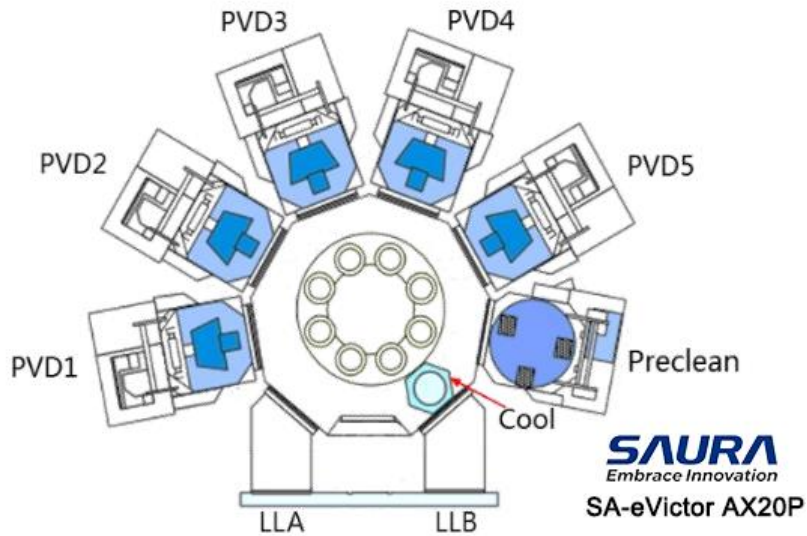
Specifications:

FSM

Parameter	Ni	Ti	TiN	Al
Wafer Size	6/8inch			
THK mean(A)	1000±50	600±30	1000±50	40K±2K
Rs Mean(Ω/□)	1±0.02	11±1.0	16±3.0	0.75±0.05
Rs U%(WIW,%,16)	< 3%	< 3%	< 3%	< 3%
Infilm Particle	< 30ea@0.3μm	< 30ea@0.3μm	< 30ea@0.3μm	< 30ea@0.3μm
W×L×H	3200×2700×2200 mm/3100×4400×2200 mm			

Principle:

3200×2700×2200 mm



3100×4400×2200 mm

